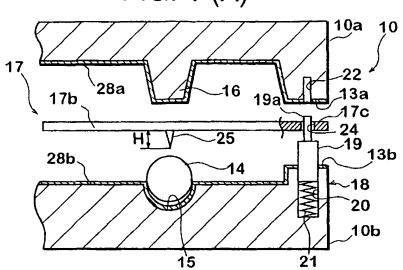
FIG. 1 (A)



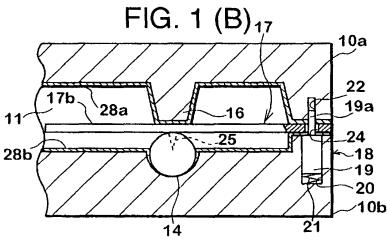
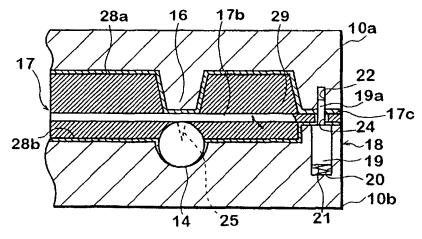
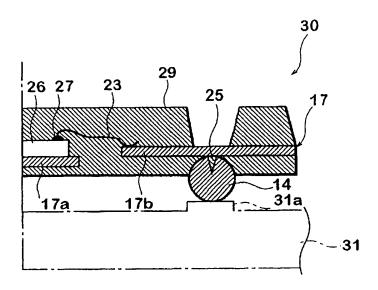


FIG. 1 (C)



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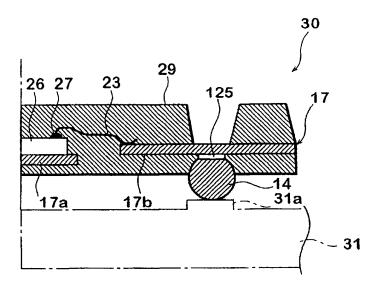
FIG. 2



PACKAGE (1)

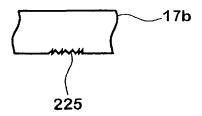
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FIG. 4



PACKAGE (2)

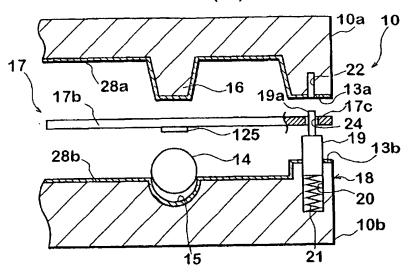
FIG. 5

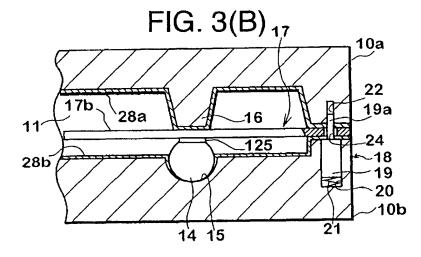


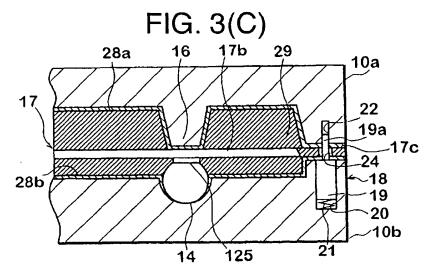
THIRD EMBODIMENT

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FIG. 3(A)

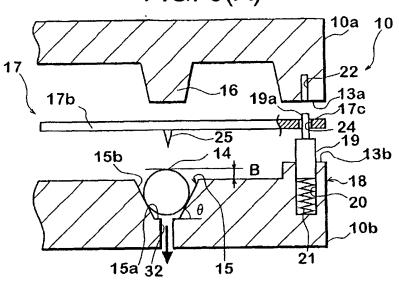


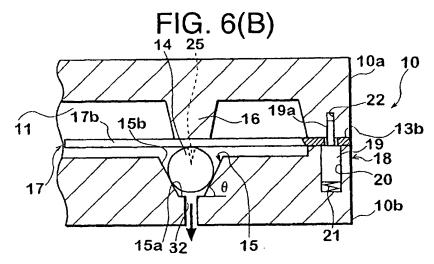


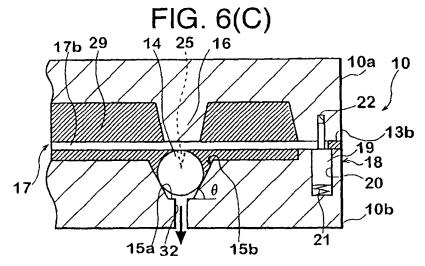


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FIG. 6(A)







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FIG. 7(A)

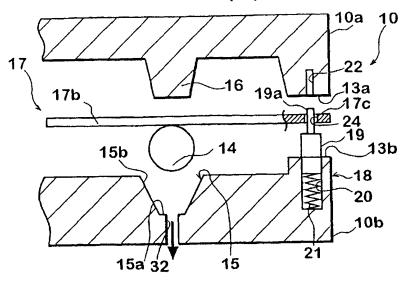


FIG. 7(B)

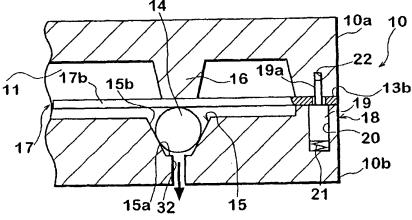


FIG. 7(C)

